



Trusted and Assured Microelectronics (T&AM): Addressing DoD Access to Advanced Packaging and Test

PROGRAM MANAGER(S): Brett Hamilton, Naval Surface Weapons Center – Crane, Technical Execution Lead

DATE: Thursday, August 20, 2020

TIME: 105 minutes

ROOM NUMBER: Virtual

ROOM NAME: Virtual

DESCRIPTION

This T&AM execution area addresses the dual problems of commanding a small market while requiring a range of unique SOTA capabilities that are critical to national security. In particular, it needs access to diverse heterogeneous integration in multi-die advanced packaging and the ecosystem of available chiplets to enable DoD system application optimization.

AGENDA

1600-1745

Heterogeneous Packaging and Test Panel

Brett Hamilton, Naval Surface Weapons Center – Crane, Advanced Packaging and Test Technical Execution Lead

Panel Members:

- Meredith Anderson Dyck, PhD, Deputy Technical Director, National Security Agency, Laboratory for Physical Sciences
- Frank Ferrante, Director Military, Aerospace and Government, Intel PSG
- Radoslav (Rocco) Bogoslovov, PhD, Principal Scientist, SETA, DARPA- MTO
- Sarah Leeper, Director, Secure & Assured Systems, Draper
- Steven Dooley, Senior Engineer, AFRL Sensors Directorate

QUESTIONS

Please contact Sydney Pope, sydney.pope.ctr@mail.mil for more information following this workshop.